

1200V 25A Trench and Field Stop IGBT

DESCRIPTION :

- High ruggedness performance
- High speed switching
- Low collector to emitter saturation voltage
- · Easy parallel switching capability
- Short circuit withstands time 10µs
- RoHS compliant.

TYPICAL APPLICATIONS:

- General inverter
- Motor driver

IGBT

MAXIMUM RATINGS (Tvj=25°C unless otherwise specified)

Characteristic	Condition	Symbol	Value	Unit
Collector-Emitter Voltage		V _{CES}	1200	V
Continuous collector current	Tc=25℃ Tc=100℃	I _{C nom}	50 25	A
Pulsed collector current	$t_{\rm P}$ limited by Tvjmax	I _{CM}	100	А
Gate emitter voltage		V_{GE}	±20	V
Short circuit withstand time		t _{sc}	10	us
Power dissipation	Tc=25℃ Tc=100℃	P _{tot}	428 214	W
Temperature under switching conditions		Tvj op	-40~+175	°C
Storage temperature		T _{STG}	-55~+150	°C

THERMAL CHARACTERISTICS

Characteristic	Condition	Symbol	Max.	Unit
IGBT thermal resistance, junction - case		$R_{th(j-C)}$	0.35	K/W
Diode thermal resistance, junction - case		$R_{th(j-C)}$	0.90	K/W
Thermal resistance, junction - ambient		R _{th(j-A)}	40	K/W



TO-247

ELECTRICAL CHARATERISTICS

Characteristic	Symbol	Min.	Тур.	Max.	Unit
Collector-emitter cut-off current VCE=1200V, VGE=0V Tvj=25°C	I _{CES}			100	uA
Gate-emitter leakage current VCE=0V, VGE=20V Tvj=25℃	I _{GES}			100	nA
Gate-Emitter threshold voltage IC=1.0mA, VGE= VCE Tvj=25℃	$V_{GE(th)}$	5.8	6.1	6.3	V
Collector-Emitter saturation voltage VGE=15V, IC=25A Tvj=25℃ VGE=15V, IC=25A Tvj=175℃	$V_{CE(SAT)}$		1.7 2.3		V
Input capacitance f=1MHz, VCE=30 V, VGE=0 V Tvj=25°C	C _{ies}		2080		pF
Output capacitance f=1MHz, VCE=30 V, VGE=0 V Tvj=25°C	C _{oes}		105		pF
Reverse transfer capacitance f=1MHz, VCE=30 V, VGE=0 V Tvj=25°C	C _{res}		20		pF
Gate charge IC = 25A, VGE = 15 V,VCC =960V Tvj=25°C	Q _G		133		nC
Turn-on delay time IC=25A, VCC=600 V Tvj=25°C VGE=0/15 V, RG=10 Ω Tvj=175°C (inductive load)	td _(ON)		31 33		ns
Rise time IC=25A, VCC=600 V Tvj=25℃ VGE=0/15 V, RG=10Ω Tvj=175℃ (inductive load)	tr		62 67		ns
Turn-off delay time IC=25A, VCC=600 V Tvj=25℃ VGE=0/15 V, RG=10Ω Tvj=175℃ (inductive load)	td (OFF)		184 206		ns
Fall time IC=25A, VCC=600 V Tvj=25℃ VGE=0/15 V, RG=10Ω Tvj=175℃ (inductive load)	tf		59 87		ns
Turn-on energy IC=25A, VCC=600 V Tvj=25℃ VGE=0/15 V, RG=10Ω Tvj=175℃ (inductive load)	E _(ON)		2.0 3.1		mJ

Turn-off energy loss per pulse IC=25A, VCC=600 V Tvj=25 $^{\circ}$ C VGE=0/15 V, RG=10 Ω Tvj=175 $^{\circ}$ C (inductive load)	E _(OFF)	0.9 1.3		mJ	
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Diode

MAXIMUM RATINGS (Tvj=25°C unless otherwise specified)

Characteristic	Condition	Symbol	Value	Unit
Repetitive peak reverse voltage	Tvj=25℃	V _{RRM}	1200	V
Continuous forward current	Tc=100℃	I _F	25	А
Diode maximum current	t_P limited by Tvj max	I _{FM}	100	А

ELECTRICAL CHARATERISTICS

Characteristic	Symbol	Min.	Тур.	Max.	Unit
Forward voltage IF=25A, VGE=0 V Tvj=25℃ IF=25A, VGE=0 V Tvj=175℃	V _F		2.0 1.6		v
Reverse Recovered Time IF=25 A, Tvj=25℃ -diF/dt =250A/µs Tvj=175℃ VR=600 V	Trr		309 480		ns
Peak reverse recovery current IF=25 A, Tvj=25°C -diF/dt =250A/µs Tvj=175°C VR=600 V	I _{RRM}		7 11		A
Reverse Recovered charge IF=25 A, Tvj=25℃ -diF/dt =250A/µs Tvj=175℃ VR=600 V	Q _{rr}		1038 3000		nC

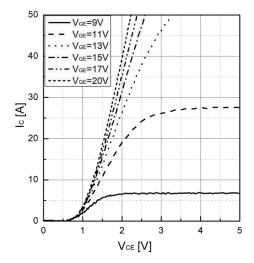


Figure 1. Typical output characteristics (Tvj=25 $^{\circ}$ C)

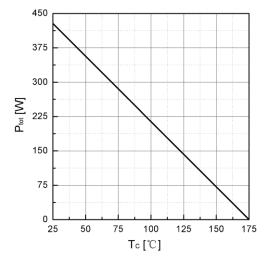


Figure 3. Power dissipation as a function of TC

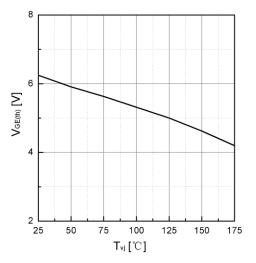


Figure 5. Typical VGE(th) as a function of Tvj ($I_C=1mA$)

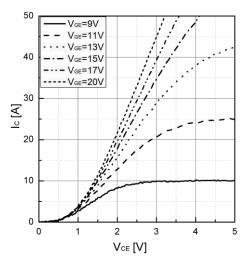


Figure 2. Typical output characteristics (Tvj=175°C)

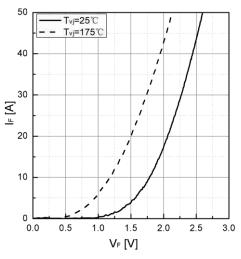


Figure 4. Typical IF as a function of VF

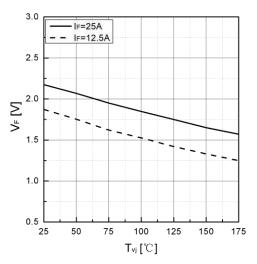


Figure 6. Typical VF as a function of Tvj

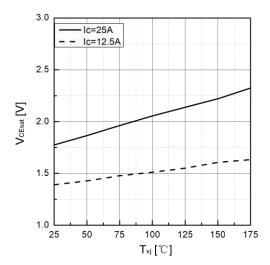


Figure 7. Typical VCEsat as a function of Tvj

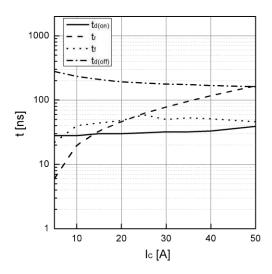


Figure 9. Typical switching times as a function of IC

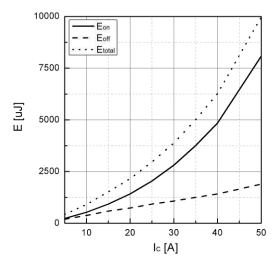


Figure 11. Typical switching energy losses as a function of IC

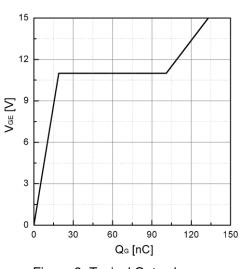


Figure 8. Typical Gate charge

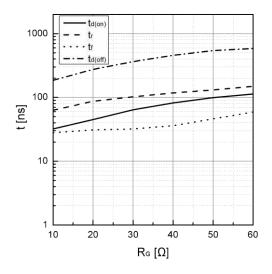


Figure 10. Typical switching times as a function of RG

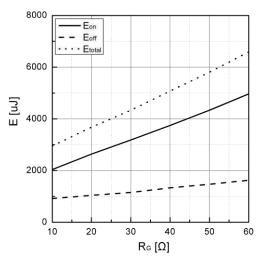
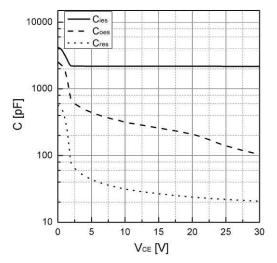
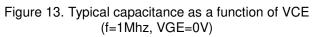


Figure 12. Typical switching energy losses as a function of RG





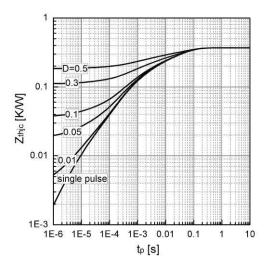
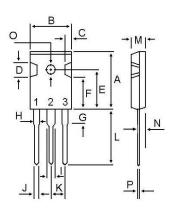


Figure 14. Transient thermal impedance, IGBT

Circuit diagram

· Package outlines : Dimensions in (mm)



	MILLIMETERS		
DIM	MIN	MAX	
A	20.80	21.80	
B	15.38	16.20	
c	1.90	2.70	
D	5.10	6.10	
E	14.50	15.50	
F	11.20	13.20	
G	3.75	4.35	
Н	1.90	2.30	
I	2.90	3.30	
J	1.00	1.40	
К	5.26	5.66	
L	19.50	20.50	
М	4.68	5.36	
N	2.30	2.60	
0	3.45	3.85	
Р	0.48	0.72	



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